Invitation SSI 2016

Just several years ago Frost and Sullivan pointed out that smart is the new green. The concept of «Smart Earth» is, in fact, the in-depth application of a new generation of network and information technologies. Smart cities arise worldwide. Global concepts for smart production are under development. The Internet of Things – IoT – including smart grid, smart health, smart city, smart buildings, smart home, smart production and smart mobility provides not only big opportunities but is requesting more highly integrated smart systems from the hardware side. The total number of connected devices is expected to grow rapidly. Electronic components and systems are a pervasive key enabling technology, impacting all industrial branches and almost all aspects of life.

The Smart Systems Integration Conference – as part of the activities of the European Technology Platform on Smart Systems Integration, EPoSS – has been a pioneer in this shift towards smartness. And so, the Smart Systems Integration Conference 2016 is already the 10th edition. SSI started in 2007 as European Conference and Exhibition and has now become a leading event at international level. For the fourth time the European Executive Congress of the MEMS Industry Group will be held in collaboration with the SSI.

The conference and exhibition addresses smart mobility, smart health, smart energy, smart production and smart society from the application point of view. Innovative smart systems, their manufacturing technologies as well as issues of integration and embedded software are also in the focus of the conference.

Within the keynote sessions two main topics will be addressed. The first one is the hardware side of the Internet of Things. The second one is printed, large area, flexible and stretchable electronics. On behalf of the committee, the Co-Chair – Dr. Guenter Lugert of Siemens AG and Chairman of EPoSS Executive Committee – and the local Co-Chairs from Germany – Prof. Christoph Kutter (Fraunhofer IZM), Klaus-Dieter Lang (Fraunhofer IZM) – I’m looking forward to receiving your application oriented or scientific submission.

Conference topics 2016

A. Applications
   A01 Smart mobility
   A02 Smart health
   A03 Smart energy
   A04 Smart society
   A05 Smart production

B. Hardware/Technologies
   B01 Design of smart integrated systems
   B02 Manufacturing of embedded micro and nano systems
   B03 Advanced micro and nano technologies
   B04 New materials for nano structures and devices
   B05 Smart low cost approaches: Full-coil technology and printed functionalities
   B06 Smart test and reliability of components and systems
   B07 System integration: 3D integration, interconnect technologies and packaging

C. Software for smart integrated systems
   C01 Embedded software
   C02 Stand-alone application software

Special topics
   Hardware for the Internet of Things
   Printed, available and flexible electronics

Smart Systems Integration
International Conference and Exhibition
   Focuses on complex systems in consideration of the components,
   Is application-oriented,
   Close to the industry and
   Shows the potential of research and development activities worldwide.

Become a speaker!

Highlight your expertise at the SSI conference with concurrent exhibition!

Your advantages at a glance
   – Present your knowledge in front of a highly qualified audience.
   – Exchange your experience with other experts.
   – Build up your personal network.
   – Benefit from maximum attention for your presentation due to extensive press work and several advertising activities.
   – Take the opportunity to win the best paper/poster award.

Deadlines
   Submission of abstracts
   5 October 2015
   Selection by committee
   10 November 2015
   Submission of full manuscripts
   25 January 2016

Online submission at
www.smartsystemsintegration.com
Committee list

Conference chair
Prof. Dr. T. Gessner, Fraunhofer ENAS, DE

Co-chair
Dr. G. Lugter, Siemens, EPoSS, DE

Local co-chair
Prof. Dr. K. Kutter, Fraunhofer EMFT, DE
Prof. Dr. K.-D. Lang, Fraunhofer IZM, DE

Scientific committee
L. Aiorgia, CEDITEC, ES
R. Aschenbrenner, Fraunhofer IZM, DE
Prof. Dr. R. R. Baumann, Fraunhofer ENAS, DE
Prof. Dr. K. Bock, TU Dresden, DE
Dr. S. Brengersma, Holst Centre, IMEC, NL
Prof. Dr. C. Cané, Centro Nacional de Microelectrónica (CNM-IMB), ES
B. Courtois, TIMA-CMP, FR
Dr. J. De Boeck, IMEC International, NL
Prof. Dr. N. F. de Rooij, EPoSS, DE
M. Desmulliez, Heriot-Watt University, GB
K. Dyrbye, Grundfos Holding, DK
Dr. S. Finkbeiner, Bosch Sensortec, DE
Prof. Dr. P. J. French, Delft University of Technology, NL
W. Gessner, VDI/VDE-IT, DE
Dr. R. Gündler, HSG IMIT, DE
Dr. C. Hedayat, Fraunhofer ENAS, DE
Dr. H. Heinzelmann, CSEM, CH
Prof. Dr. C. Hierold, ETH, CH
Prof. Dr. K. Hiller, Chemnitz University of Technology, DE
D. Holden, CEA-LETI, FR
Dr. J. Hilmalmi, VTT Technical Research Centre of Finland, FI
Dr. C. Mervelle, KEKLAN, ES
Prof. Dr. W. Mukwa, RWTH Aachen, DE
Dr. A. Muller, IHT, RO
A. P. Myrsten, DELTA, DK
A. Nebelung, Elmos, DE
Prof. H.-E. Nilsson, Mid Sweden University, SE
Prof. Dr. T. Otto, Fraunhofer ENAS, DE
Prof. Dr. H. Persina Neves, Six Semiconductors, BR
P. Perlo, Interactive Fully Electric Vehicle, IT
Dr. A. Perret, CSEM, CH

Submission requirements

Conference chair
English

Dr. I. V. Popova, Gyrooptics, RU
G. Poupon, CEA-LETI, FR
Dr. M. Riester, maritecchon Dr. Markus Riester, AT
Dr. M. Rigoni, Istituto di Fisica Applicata Nello Carrara Firenze, IT
V. Rouet, EADS France – Innovation Works, FR
Prof. A. Rydborg, University of Uppsala, SE
Prof. Dr. S. Rzepka, Fraunhofer ENAS, DE
Dr. M. Scholles, Fraunhofer IPMS, DE
U. Schwarz, X-FAB, DE
T. Stärz, micro FAB, DE
Dr. N. Thyssen, Infineon, DE
Prof. J. Tuovinen, Trinity College Dublin, IR
Dr. M. van der Beek, Philips Research, NL
J. Wolf, Fraunhofer IZM, DE
Prof. Dr. R. Zengerle, IMTEK, DE

Advisory committee
International members
Prof. Dr. M. Esashi, Tohoku University, JP
R. H. Grace, R. Grace Associates, US
K. Lightman, MEMS Industry Group, US
Prof. Z. Zhou, Tsinghua University Beijing, CN

Members of EPoSS advisory committee
B. Candaella, Thales, FR
R. Dal Molin, SORIN CRM, FR
N. Di Giusta, Centro Ricerche Fiat, IT
R. Griggi, Ideas & Motion, IT
K. Hofmann, Continental Automotive, DE
A. Karhonen, Murata Electronics, FI
Dr. J. Langheim, STMicroelectronics International, FR
Dr. R. Neel, Bosch, DE
A. Nguyen-Dinh, Verb, FR
H. Rödig, Infineon Technologies, DE
Dr. W. van Driel, Philips Electronics, NL

Dr. W. van Driel, Infineon Technologies, NL

Conference language
English

Submission no later than 5 October 2015
at www.smartsystemsintegration.com

Conference language
English

Conditions of acceptance
Authors are expected to secure the registration fee of 305 EUR + VAT as well as travel and accommodation funding through their sponsoring organizations, before submitting abstracts. Full payment will be due once the submission has been accepted. Only original material should be submitted. Government and company clearance must be obtained to publish and be at the time of submission. Non-research based papers which attempt to promote commercial products cannot be submitted.

Selection process
The committee will review all submitted abstracts to maintain the high quality of the conference. Only papers submitted on time and addressing subjects which are topical and relevant to the conference will be considered for inclusion in the conference programme. Submitted papers may be selected for oral or poster presentations.

Venue
Following Paris, Barcelona, Brussels, Como, Dresden, Zurich, Amsterdam, Vienna and Copenhagen, the 2016 event is held in Munich, Germany. The Holiday Inn Munich – City Centre is one of the largest business hotels in the south of Germany. It is situated next to the historical city centre. There’s direct access to the station »Rosenheimer Platz« getting to other destinations like Munich International Airport, the main train station and Greater Munich is as easy as can be. Munich has excellent flight and railway connections. For more information visit: www.munich-meeting-centre.de

Impressions of SSI 2015

Oral and poster presentations
Oral presentations will be held in different sessions. The duration of each presentation should not exceed 25 minutes including 5 minutes for subsequent discussions. Poster authors will have the opportunity to present their posters during a special poster session and throughout the conference. All oral and poster presentations will be included in the conference proceedings.

Tutorials
Tutorials are designed to provide in-depth knowledge on special topics. They should include hands-on activities or demonstrations, illustrated by means of examples and widely agreed solutions. Tutorials can be led by one or more speakers and should not exceed 3 hours.

Submission
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